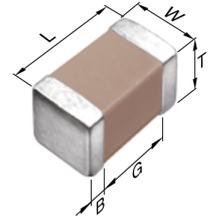


C1608JB0G226M080AA



TDK item description C1608JB0G226MT****

| | |
|---------------------|---|
| Applications | Commercial Grade |
| Feature | General General (Up to 50V) |
| Series | C1608 [EIA 0603] |
| Status | Production |



Dimensions in mm

| Size | |
|-------------------------------|------------------------------------|
| Length(L) | 1.60mm +0.20,-0.10mm |
| Width(W) | 0.80mm +0.20,-0.10mm |
| Thickness(T) | 0.80mm +0.20,-0.10mm |
| Terminal Width(B) | 0.20mm Min. |
| Terminal Spacing(G) | 0.30mm Min. |
| Recommended Land Pattern (PA) | 0.70mm to 1.00mm(Flow Soldering) |
| | 0.60mm to 0.80mm(Reflow Soldering) |
| Recommended Land Pattern (PB) | 0.80mm to 1.00mm(Flow Soldering) |
| | 0.60mm to 0.80mm(Reflow Soldering) |
| Recommended Land Pattern (PC) | 0.60mm to 0.80mm(Flow Soldering) |
| | 0.60mm to 0.80mm(Reflow Soldering) |

| Electrical Characteristics | |
|------------------------------|-----------|
| Capacitance | 22μF ±20% |
| Rated Voltage | 4VDC |
| Temperature Characteristic | JB(±10%) |
| Dissipation Factor (Max.) | 10% |
| Insulation Resistance (Min.) | 4MΩ |

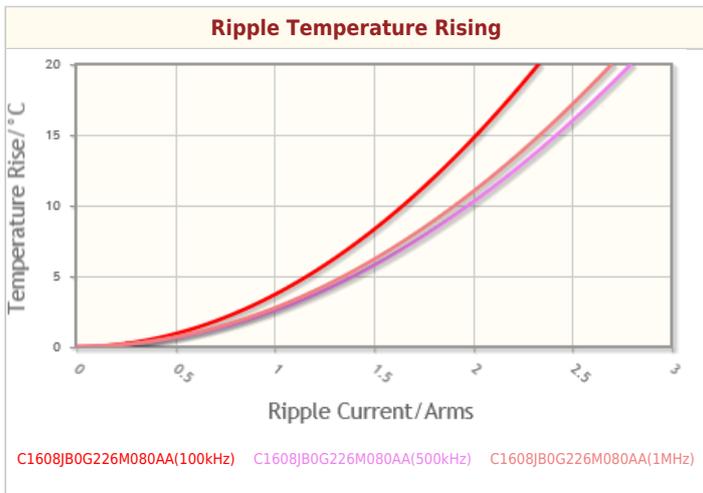
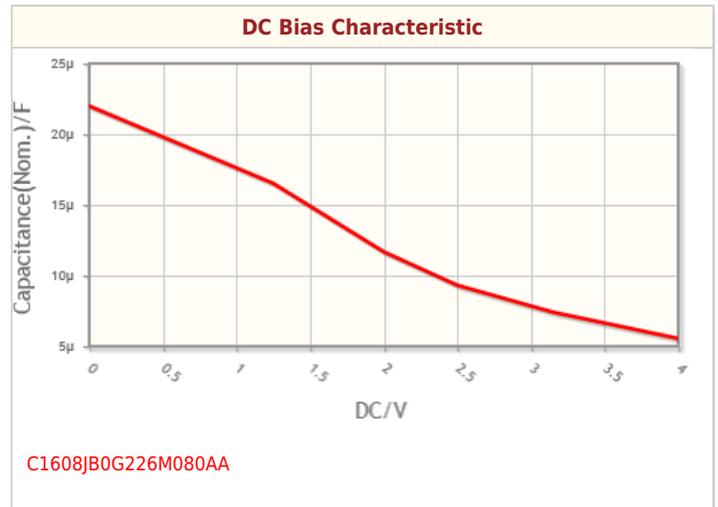
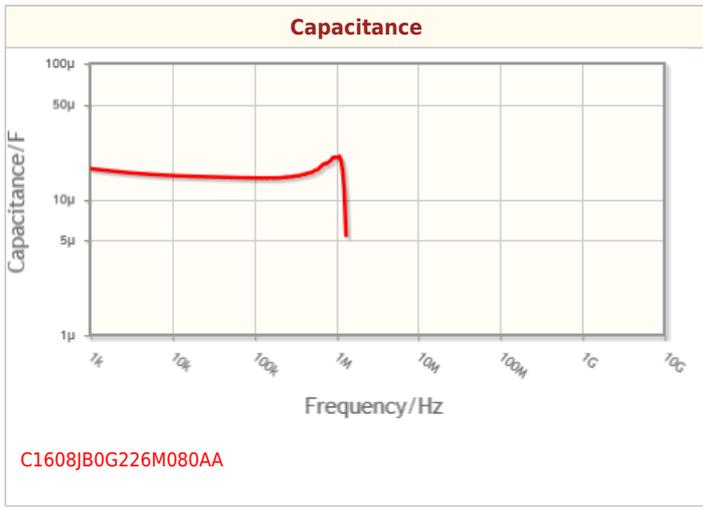
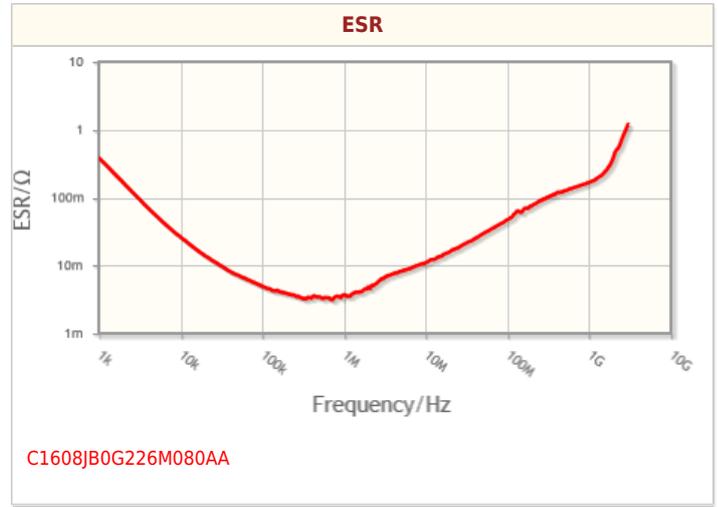
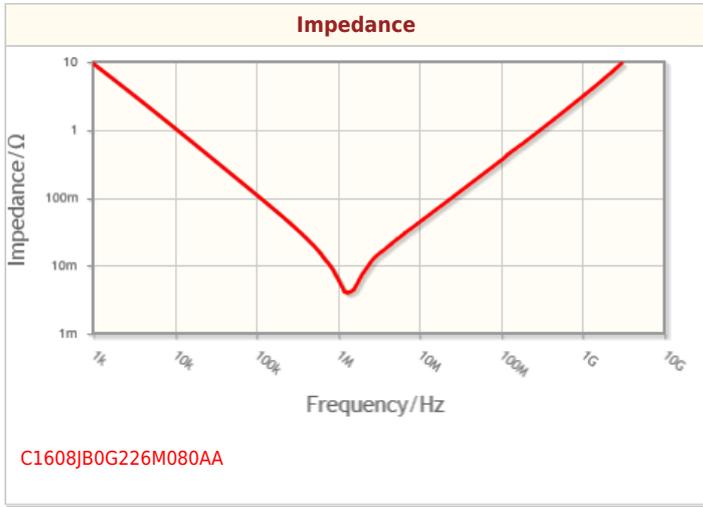
| Other | |
|------------------|------------------------------------|
| Soldering Method | Wave (Flow) |
| | Reflow |
| AEC-Q200 | No |
| Packing | Punched (Paper)Taping [180mm Reel] |
| Package Quantity | 4000pcs |

! Images are for reference only and show exemplary products.
! This PDF document was created based on the data listed on the TDK Corporation website.
! All specifications are subject to change without notice.

C1608JB0G226M080AA



Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)



! Images are for reference only and show exemplary products.
! This PDF document was created based on the data listed on the TDK Corporation website.
! All specifications are subject to change without notice.

C1608JB0G226M080AA



Associated Images

